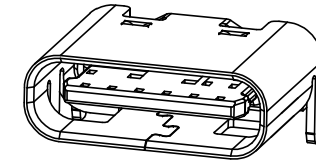
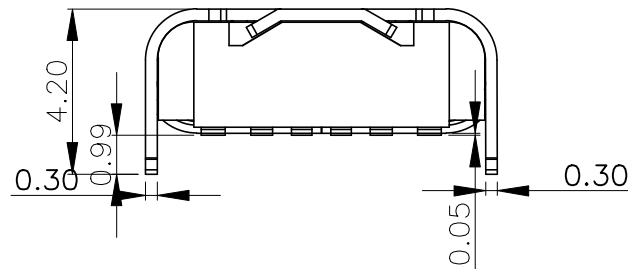
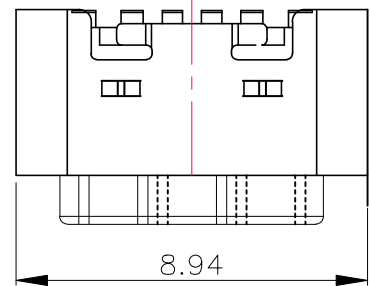


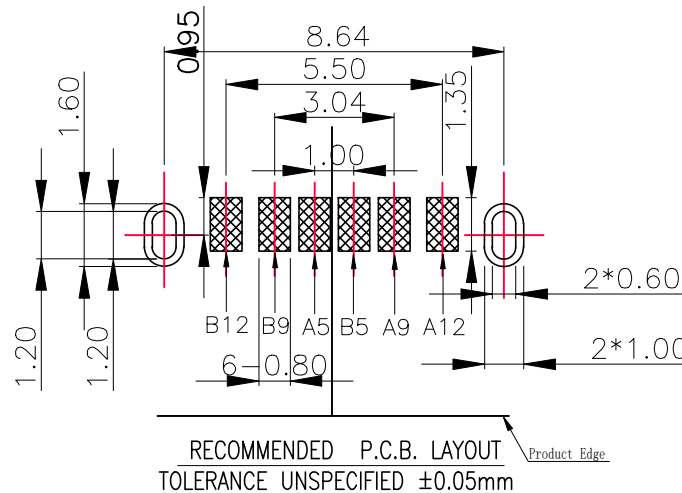
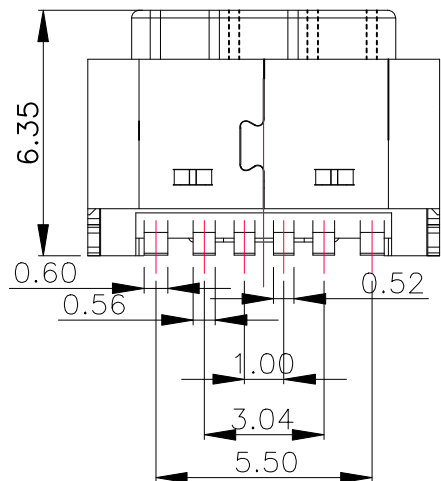
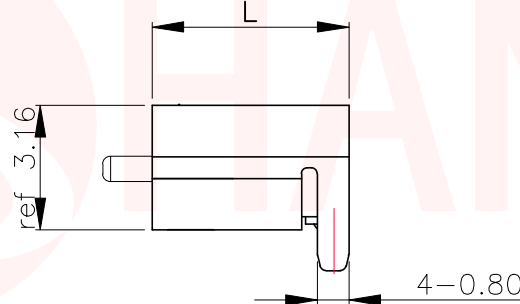
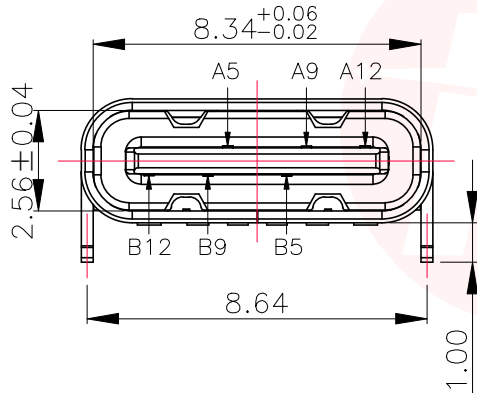


REV.	ECN NO OR DESCRIPTION	REVISED	DATE



NOTE:

- 1.MATERIAL SPECIFICATION:**
 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
 2.CONTACTS:COPPER ALLOY
 3.MID PLATE: STAINLESS STEEL
 4.FRONT SHELL: STAINLESS STEEL
- 2.PLATING SPECIFICATION:**
 2-1.CONTACTS:
 Ni 50u" MIN. UNDER PLATED OVER ALL.
 Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
 (GOLD PLATING THICKNESS FOLLOW THE P/N)
 PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
- 2-2.FRONT SHELL:
 SEE TABLE1.
- 2-3.SHIELD PLATE&EMI PLATE:
 CLEAR ONLY
- 3.MECHANICAL PERFORMANCE,**
 3-1.INSERTION FORCE: 0.5~2.0kgf.
 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
 3-3.DURABILITY: 5000 CYCLES.
- 4.ELECTRICAL PERFORMANCE,**
 4-1. CURRENT RATING:3.0A
 VOLTAGE RATING:5.0V
- 4-2. LLCR:
 VBUS & GND PINS AND OTHER PINS: 40mA/PIN MAX.
 SHIELD: 50mA/MAX.
 LLCR MAX. CHANGE OF ALL PINS: 10mA.
- 4-3.INSULATION RESISTANCE: 100MΩ MIN
 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.
- 5. ENVIRONMENTAL PERFORMANCE:**
 OPERATING TEMPERATURE: -25°C~+85°C.
- 6.IR REFLOW:**
 THE PEAK TEMPERATURE ON THE BOARD SHALL
 BE MAINTAINED FOR 10 SECONDS AT 260°C.



PIN ASSIGNMENTS

A5	CC1	B12	GND
A9	VBUS	B9	VBUS
A12	GND	B5	CC2
PIN	SIGNAL NAME	PIN	SIGNAL NAME

PART No.	DIM L
MC-311D-H50	5.0
MC-311D-H55	5.5
MC-311D-H65	6.5
MC-311D-H68	6.8

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.30	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.10	



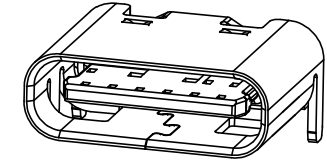
东莞市汉博电子科技有限公司
 DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	TYPE C 6P 板上后两脚插板SMT			
DWN	xiong	PART NO. MC-311D-HXXX		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:1OF 1	REV: A4

CUSTOMER COPY



REV.	ECN NO OR DESCRIPTION	REVISED	DATE



NOTE:

- MATERIAL SPECIFICATION:**
 - HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
 - CONTACTS: COPPER ALLOY
 - MID PLATE: STAINLESS STEEL
 - FRONT SHELL: STAINLESS STEEL
- PLATING SPECIFICATION:**
 - CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW THE P/N)
 - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - FRONT SHELL: SEE TABLE1.
 - SHIELD PLATE&EMI PLATE: CLEAR ONLY
- MECHANICAL PERFORMANCE,**
 - INSERTION FORCE: 0.5~2.0kgf.
 - REMOVAL FORCE: 0.8kgf~2.0kgf.
 - DURABILITY: 5000 CYCLES.
- ELECTRICAL PERFORMANCE,**
 - CURRENT RATING: 3.0A
VOLTAGE RATING: 5.0V
 - LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40ma/PIN MAX.
 - SHIELD: 50ma/MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10ma.
 - INSULATION RESISTANCE: 100MΩ MIN
 - DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
- ENVIRONMENTAL PERFORMANCE:**
 - OPERATING TEMPERATURE: -25°C~+85°C.
- IR REFLOW:**
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.

PIN ASSIGNMENTS

PIN	SIGNAL NAME	PIN	SIGNAL NAME
A5	CC1	B12	GND
A9	VBUS	B9	VBUS
A12	GND	B5	CC2

PART No.	DIM L
MC-311D-H50	5.0
MC-311D-H55	5.5
MC-311D-H65	6.5
MC-311D-H68	6.8

UNLESS OTHERWISE SPECIFIED TOLERANCES



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

DECIMALS: X :±0.30 X.X :±0.20 X.XX :±0.10
 ANGLES: X :±2° X.X :±1°

TITLE	TYPE C 6P 板上后两脚插板SMT			
DWN	xiong	PART NO. MC-311D-HXXX		
CHKD	lee	SCALE: 1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET: 1 OF 1	REV: A4

CUSTOMER COPY

RECOMMENDED P.C.B. LAYOUT
TOLERANCE UNSPECIFIED ±0.05mm

